

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A Final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

Technical Contact:

Name: Yeoh, LiangChoon
E-mail: Liang.Yeoh@fairchildsemi.com
Phone: 8502744

PCN Originator:

Name: Chiah, BoonHwa
E-mail: BoonHwa.Chiah@fairchildsemi.com
Phone: 8502357

Implementation of change:

Expected 1st Device Shipment Date: 2008/04/28

Earliest Year/Work Week of Changed Product: 0824

Change Type Description: Mold Compound

Description of Change (From): TSSOP package assembly at all FSC approved manufacturing locations using non Green mold compound as shown in table 1.

Description of Change (To): TSSOP package assembly at all FSC approved manufacturing locations using Green mold compound as shown in table 2.

Reason for Change : Green initiative by Fairchild Semiconductor. Fairchild Semiconductor is dedicated to being a good corporate citizen. All Fairchild Semiconductor products are 2nd level interconnect lead-free and RoHS compliance. The referenced material changes have been made to provide a 'Full Green' (Halogen Free Flame Retardant) package. For additional details on the corporate wide green initiative please visit our Web site at : <http://www.fairchildsemi.com/company/green/index.html> Manufacturing will occur at the same assembly facilities producing the current non-green products. Package outline drawings of the affected products remain un-changed. Green products will be fully compliant to all published data sheet specifications and will be interchangeable with current non-green product. Quality and reliability will remain at the highest standards already demonstrated with Fairchild's existing products.

Qual/REL Plan Numbers : Q20070049

Qualification :

To qualify Sumitomo G700K green mold compound as a replacement for Sumitomo EME 6730B and EME 7050 type B at Amkor for assembly of TSSOP packages for the system Power and Logic product families.

Change From

TABLE 1			
Assembly site	Amkor		
Generic Package	NMTC0	NMTD0	MNTF0
Substrate	C7025	C7025	C7025
Die Attach	Ablestick 8340	84-1LMISR4	Ablestick 8290
Wire	1.0 mil, Au	1.0 mil, Au	2.0mils, Au
Mold Compound	Sumitomo 6730B	Sumitomo 7351T	Sumitomo 7050B
Lead Finish	Matte Sn	Matte Sn	Matte Sn

Change To

TABLE 2			
Assembly site	Amkor		
Generic Package	NMTC0	NMTD0	MNTF0
Substrate	C7025	C7025	C7025
Die Attach	Ablestick 8290	Ablestick 8290	Ablestick 8290
Wire	1.0 mil, Au	1.0 mil, Au	2.0mils, Au
Mold Compound	Sumitomo G700K	Sumitomo G700K	Sumitomo G700K
Lead Finish	Matte Sn	Matte Sn	Matte Sn

Qualification Stress Test and Sample Size Detail

Device #1	FAN1655MTFX
Package:	NMTF0
#Leads:	016

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints		Samples
Stress	P/C	Standard	Conditions	TP1	TP2	A
DOPL		JESD22-A108	125C, 0V	168	1000	77
HAST2	X	JESD22-A110	85%RH, 110C, 0V	264		45
HTSL	X	JESD22-A103	150C	168	1000	77
TMCL1	X	JESD22-A104	125C, 0C	500		77

Device #2	FAN5019MTCX
Package:	NMTC0
#Leads:	028

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL2A		JESD22-A113			0

Environment Stress Detail:

				Readpoints		Samples
Stress	P/C	Standard	Conditions	TP1	TP2	A
DOPL		JESD22-A108	125C, 0V	168	1000	77

HTSL	X	JESD22-A103	150C	168	1000	77
THBT	X	JESD22-A101	85%RH, 85C, 0V	186	1000	77
TMCL1	X	JESD22-A104	-65C, 150C	500		77

Device #3	GTLP16T1655MTDX
Package:	NMTD0
#Leads:	064

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL3A		JESD22-A113			0

Environment Stress Detail:

				Readpoints		Samples
Stress	P/C	Standard	Conditions	TP1	TP2	A
GATE+		AEC-Q100-006	155C, 400V	1		3
GATE-		AEC-Q100-006	155C, -400V	1		3
HTSL	X	JESD22-A103	150C	168	1000	77
SOPL1	X	JESD22-A108	150C, 0V	168	1000	77
THBT	X	JESD22-A101	85%RH, 85C, 0V	168	1000	77
TMCL1	X	JESD22-A104	-65C, 150C	500		77

Device #4	SSTV16859MTDX
Package:	NMTD0
#Leads:	064

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL3A		JESD22-A113			0

Environment Stress Detail:

				Readpoints		Samples
Stress	P/C	Standard	Conditions	TP1	TP2	A
GATE+		AEC-Q100-006	155C, 400V	1		3
GATE-		AEC-Q100-006	155C, -400V	1		3
HTSL	X	JESD22-A103	150C	168	1000	77
SOPL1	X	JESD22-A108	150C, 0V	168	1000	77
THBT	X	JESD22-A101	85%RH, 85C, 0V	168	1000	77
TMCL1	X	JESD22-A104	-65C, 150C	500		77

Product Id Description :

Affected FSIDs :

74VCX16722MTD	74VCX16722MTDX	FAN1655MTFX
FAN5019MTC	FAN5019MTCX	FAN5026MTC
FAN5026MTCX	FAN5232MTC	FAN5232MTCX
FAN5236MTC	FAN5236MTCX	FAN5240MTC
FAN5240MTCX	GTLP16T1655MTD	GTLP16T1655MTDX
SSTV16859MTD	SSTV16859MTDX	